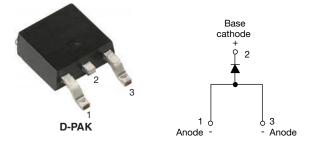




Vishay Semiconductors

## Surface Mount Fast Soft Recovery Rectifier Diode, 8 A



PRODUCT SUMMARY							
Package	D-PAK (TO-252AA)						
I <sub>F(AV)</sub>	8 A						
V <sub>R</sub>	200 V, 400 V, 600 V						
V <sub>F</sub> at I <sub>F</sub>	1.2 V						
I <sub>FSM</sub>	150 A						
t <sub>rr</sub>	55 ns						
T <sub>J</sub> max.	150 °C						
Diode variation	Single die						
Snap factor	0.5						

#### **FEATURES**

- Meets MSL level 1, per J-STD-020, LF maximum of 260 °C RoHS
- Material categorization: For definitions of COMPLIANT compliance please see <u>www.vishay.com/doc?99912</u>

### DESCRIPTION

The VS-8EWF..SPbF fast soft recovery rectifier series has been optimized for combined short reverse recovery time, low forward voltage drop and low leakage current.

The glass passivation ensures stable reliable operation in the most severe temperature and power cycling conditions.

This series is designed and qualified for industrial level.

#### APPLICATIONS

- Output rectification and freewheeling diode in inverters, choppers and converters
- Input rectifications where severe restrictions on conducted EMI should be met

MAJOR RATINGS AND CHARACTERISTICS										
SYMBOL	CHARACTERISTICS	VALUES	UNITS							
I <sub>F(AV)</sub>	Sinusoidal waveform	8	A							
V <sub>RRM</sub>		200 to 600	V							
I <sub>FSM</sub>		150	А							
V <sub>F</sub>	8 A, T <sub>J</sub> = 25 °C	1.2	V							
t <sub>rr</sub>	1 A, 100 A/µs	55	ns							
TJ	Range	-40 to 150	°C							

VOLTAGE RATINGS										
PART NUMBER	V <sub>RRM</sub> , MAXIMUM PEAK REVERSE VOLTAGE V	V <sub>RSM</sub> , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I <sub>RRM</sub> AT 150 °C mA							
8EWF02SPbF	200	300								
8EWF04SPbF	400	500	3							
8EWF06SPbF	600	700								

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Maximum average forward current	I <sub>F(AV)</sub>	$T_C = 96 \ ^{\circ}C$ , 180° conduction half sine wave	8						
Maximum peak one cycle	I <sub>FSM</sub>	10 ms sine pulse, rated V <sub>RRM</sub> applied	125	A					
non-repetitive surge current		10 ms sine pulse, no voltage reapplied	150						
Maximum I <sup>2</sup> t for fusing	l <sup>2</sup> t	10 ms sine pulse, rated V <sub>RRM</sub> applied	78	A <sup>2</sup> s					
Maximum - t for fusing		10 ms sine pulse, no voltage reapplied	110	A-2					
Maximum I <sup>2</sup> $\sqrt{t}$ for fusing I <sup>2</sup> $\sqrt{t}$		t = 0.1 ms to 10 ms, no voltage reapplied	1100	A²√s					

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ELECTRICAL SPECIFICATIONS									
PARAMETER	SYMBOL	TEST CO	VALUES	UNITS					
Maximum forward voltage drop	V <sub>FM</sub>	8 A, T <sub>J</sub> = 25 °C	1.2	V					
Forward slope resistance	r <sub>t</sub>	T <sub>.1</sub> = 150 °C	16	mΩ					
Threshold voltage	V <sub>F(TO)</sub>	1j = 150 C	1.13	V					
Maximum reverse leakage current	I <sub>RM</sub>	T <sub>J</sub> = 25 °C	V - Reted V	0.1	mA				
Maximum reverse leakage current		T <sub>J</sub> = 150 °C	V <sub>R</sub> = Rated V <sub>RRM</sub>	3					

RECOVERY CHARACTERISTICS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	· •				
Reverse recovery time	t <sub>rr</sub>	Lat 8 A	200	ns	I <sub>FM</sub> t				
Reverse recovery current	l <sub>rr</sub>	I <sub>F</sub> at 8 A <sub>pk</sub> 25 A/μs	2.6	А					
Reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C	0.25	μC					
Snap factor	S		0.5		∣ ¥∠ I <sub>rr</sub>				

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	R SYMBOL TEST CONDITIONS VALUES							
Maximum junction and storage temperature range	I storage T <sub>J</sub> , T <sub>Stg</sub>		-40 to 150	°C				
Soldering temperature	Τ <sub>S</sub>	For 10 seconds	260					
Maximum thermal resistance, junction to case	R <sub>thJC</sub>	DC operation	2.5	°C/W				
Typical thermal resistance, junction to ambient (PCB mount)	R <sub>thJA</sub> <sup>(1)</sup>		50	C/W				
Approvimeto weight			1	g				
Approximate weight			0.03	oz.				
Marking device		Case style TO-252AA (D-PAK)	8EWF06S					

Note

(1) When mounted on 1" square (650 mm<sup>2</sup>) PCB of FR-4 or G-10 material 4 oz. (140 µm) copper 40 °C/W For recommended footprint and soldering techniques refer to application note #AN-994



### VS-8EWF..SPbF Soft Recovery Series

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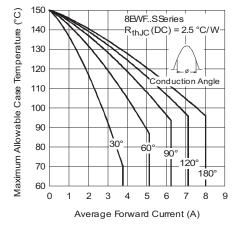


Fig. 1 - Current Rating Characteristics

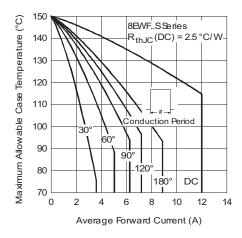


Fig. 2 - Current Rating Characteristics

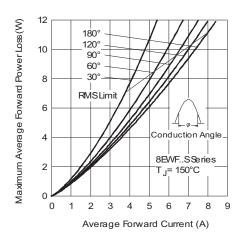


Fig. 3 - Forward Power Loss Characteristics

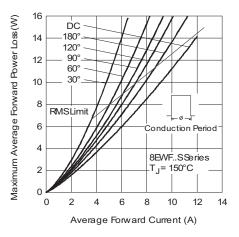


Fig. 4 - Forward Power Loss Characteristics

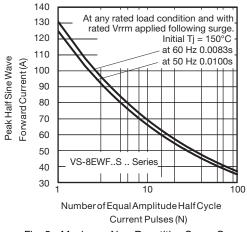


Fig. 5 - Maximum Non-Repetitive Surge Current

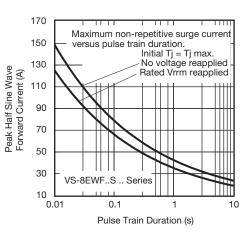


Fig. 6 - Maximum Non-Repetitive Surge Current

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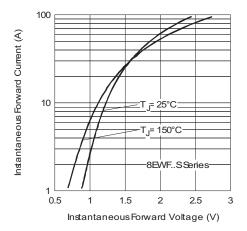


Fig. 7 - Forward Voltage Drop Characteristics

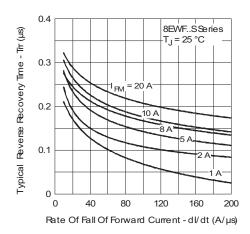


Fig. 8 - Recovery Time Characteristics,  $T_J$  = 25  $^\circ C$ 

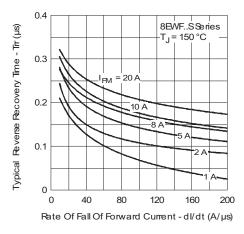


Fig. 9 - Recovery Time Characteristics,  $T_J$  = 150  $^\circ C$ 

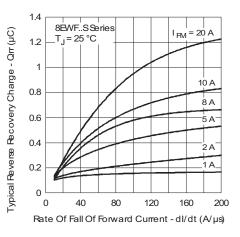


Fig. 10 - Recovery Charge Characteristics, T<sub>J</sub> = 25 °C

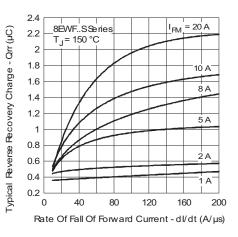


Fig. 11 - Recovery Charge Characteristics,  $T_J = 150$  °C

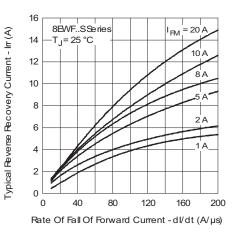


Fig. 12 - Recovery Current Characteristics, T<sub>J</sub> = 25 °C

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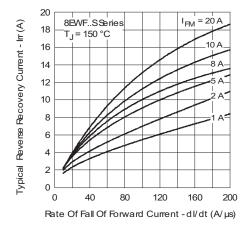


Fig. 13 - Recovery Current Characteristics,  $T_J$  = 150 °C

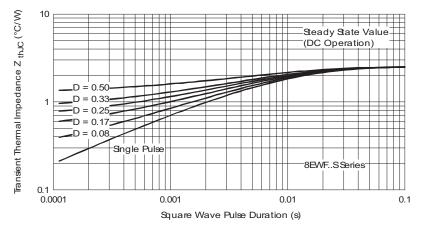
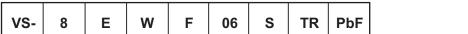
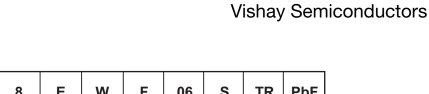


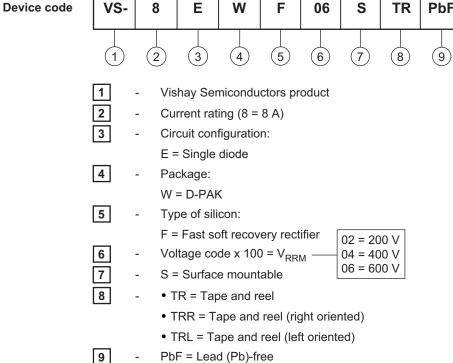
Fig. 14 - Thermal Impedance Z<sub>thJC</sub> Characteristics

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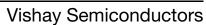
LINKS TO RELATED DOCUMENTS							
Dimensions	www.vishay.com/doc?95016						
Part marking information	www.vishay.com/doc?95059						
Packaging information	www.vishay.com/doc?95033						
SPICE model	www.vishay.com/doc?95551						

/ISHA`

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**ORDERING INFORMATION TABLE** 

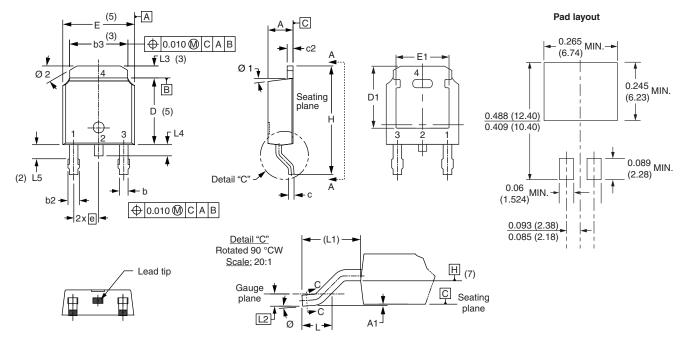
VS-8EWF..SPbF Soft Recovery Series





D-PAK (TO-252AA)

#### **DIMENSIONS** in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STIVIDOL	MIN.	MAX.	MIN.	MAX.	NOTES	STIVIDUL	MIN.	MAX.	MIN.	MAX.	NOTES
А	2.18	2.39	0.086	0.094		е	2.29	BSC	0.090	BSC	
A1	-	0.13	-	0.005		Н	9.40	10.41	0.370	0.410	
b	0.64	0.89	0.025	0.035		L	1.40	1.78	0.055	0.070	
b2	0.76	1.14	0.030	0.045		L1	2.74	BSC	0.108	REF.	
b3	4.95	5.46	0.195	0.215	3	L2	0.51	BSC	0.020	BSC	
с	0.46	0.61	0.018	0.024		L3	0.89	1.27	0.035	0.050	3
c2	0.46	0.89	0.018	0.035		L4	-	1.02	-	0.040	
D	5.97	6.22	0.235	0.245	5	L5	1.14	1.52	0.045	0.060	2
D1	5.21	-	0.205	-	3	Ø	0°	10°	0°	10°	
E	6.35	6.73	0.250	0.265	5	Ø1	0°	15°	0°	15°	
E1	4.32	-	0.170	-	3	Ø2	25°	35°	25°	35°	

#### Notes

<sup>(1)</sup> Dimensioning and tolerancing as per ASME Y14.5M-1994

(2) Lead dimension uncontrolled in L5

<sup>(3)</sup> Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad

(4) Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip

(5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

<sup>(6)</sup> Dimension b1 and c1 applied to base metal only

<sup>(7)</sup> Datum A and B to be determined at datum plane H

<sup>(8)</sup> Outline conforms to JEDEC outline TO-252AA

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